



PK668 (v1.0) Oct 3, 2014

# 100% Material Declaration Data Sheet for Spartan-3AN FT256 Cu Wire Package

**Average Weight: 0.7700 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die 1</b>					<b>0.010425</b>	<b>1.354%</b>
	Silicon	7440-21-3	100.00		0.010425	
<b>Silicon Die 2</b>					<b>0.001608</b>	<b>0.209%</b>
	Silicon	7440-21-3	100.00		0.001608	
<b>Die Attach</b>					<b>0.002719</b>	<b>0.353%</b>
	Silver	7440-22-4	77.50		0.002107	
	Bismaleimide monomer	trade secret	15.00		0.000408	
<b>Film</b>					<b>0.000007</b>	<b>0.001%</b>
	Solid Epoxy Resin	NA	12.50		0.000001	
	Phenol Resin	NA	12.50		0.000001	
	Amorphous Silica	7631-86-9	35.00		0.000002	
<b>Mold Compound</b>					<b>0.392035</b>	<b>50.914%</b>
	Epoxy Resin	Trade secret	7.50		0.029403	
	Phenol Resin A	9003-35-4	3.00		0.011761	
	Phenol Resin B	Trade secret	3.00		0.011761	
	Silica(Amorphous) A	60676-86-0	67.95		0.266388	
	Silica(Amorphous) B	7631-86-9	15.00		0.058805	
	Metal Hydroxide	Trade secret	3.00		0.011761	
Carbon black	1333-86-4	0.55		0.002156		
<b>Copper Wire</b>					<b>0.002610</b>	<b>0.339%</b>
	Copper	7440-50-8	98.25		0.002564	
	Palladium	7440-05-3	1.75		0.000046	
<b>Gold Wire</b>					<b>0.000222</b>	<b>0.029%</b>
	Gold	7440-57-5	99.05		0.000220	
	Palladium	7440-05-3	0.95		0.000002	
<b>Solder Ball</b>					<b>0.141093</b>	<b>18.324%</b>
	Tin	7440-31-5	63.00		0.088889	
	Lead	7439-92-1	37.00		0.052204	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Substrate</b>					<b>0.219281</b>	<b>28.478%</b>
	Gold	7440-57-5	1.39		0.003042	
	Nickel	7440-02-0	13.47		0.029536	
	Copper Plating	7440-50-8	25.78		0.056520	
	Continuous Filament Fiber Glass	65997-17-3	13.06		0.028638	
	BT Core	7440-50-8	39.18		0.085914	
	Solder mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6	7.13		0.015631	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
10/03/2014	1.0	Xilinx Initial Release

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